Special Issue

Surface and Bulk Acoustic Wave Devices

Message from the Guest Editors

Surface Acoustic Wave (SAW) and Bulk Acoustic Wave (BAW) devices are pivotal in various applications across telecommunications, consumer electronics, and sensor systems. These devices capitalize on acoustic waves to provide solutions for signal processing, sensing, and actuation at microscale levels. In this Special Issue, we aim to showcase cutting-edge research that highlights the development, optimization, and application of SAW and BAW devices. Contributions may cover a range of topics including, but not limited to, novel fabrication techniques, material innovations, theoretical modeling, and application-driven studies of these devices in new and existing fields. We invite researchers and practitioners to share their insights and findings that contribute to pushing the boundaries of what is possible with acoustic wave technology.

Guest Editors

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Deadline for manuscript submissions

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